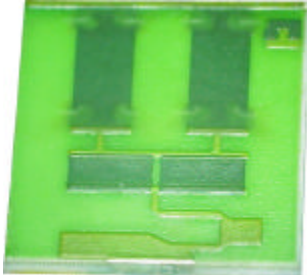




Surface Mount Termination 100 Watts, 50W



Description

The RFP-500500A6Z50 is a high performance Alumina (Al₂O₃) surface mount termination intended as a lower cost alternative to Aluminum Nitride (AlN) and Beryllium Oxide (BeO). The SMD termination is well suited to all cellular frequency bands such as: AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating 90° hybrids, directional couplers, and for use in isolators.

General Specifications

Resistive Element	Thick film
Substrate	Alumina Ceramic
Terminal Finish	Thick film Silver
Operating Temperature	-55 to +125°C (see chart)

Tolerance is ±0.010", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

Electrical Specifications

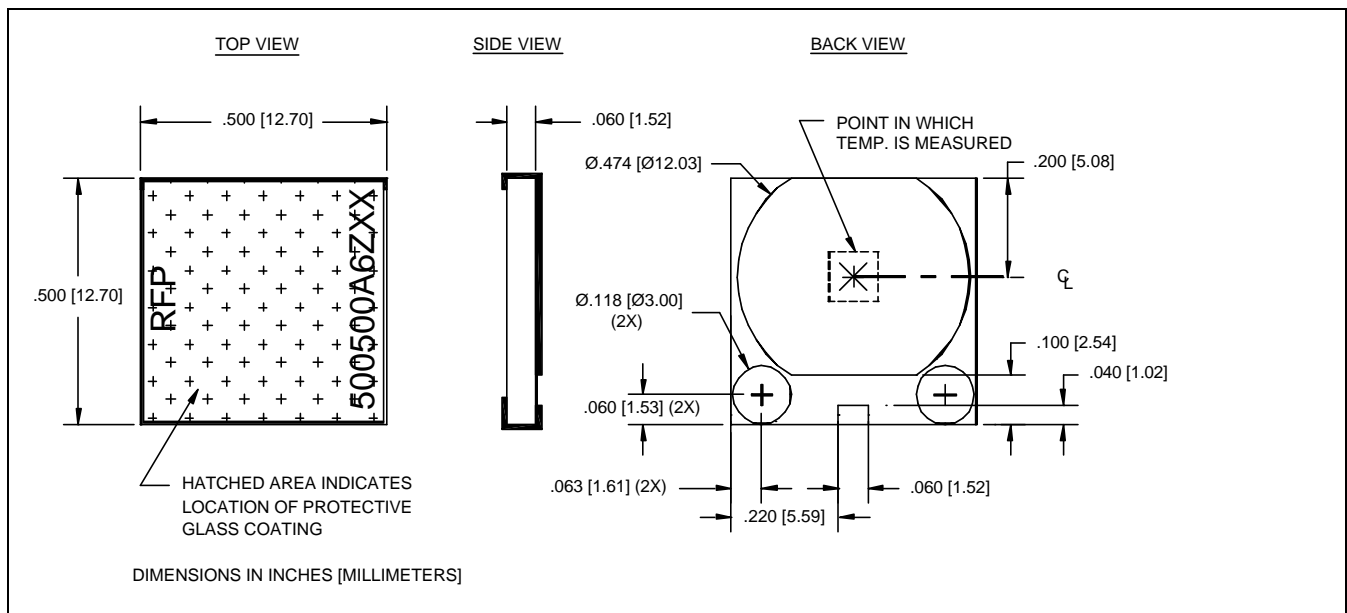
Resistance Value:	50 ohms, ± 2%
Power:	100 Watts
Frequency Range:	1KHz – 2.3GHz
V.S.W.R.:	<1.22:1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change without notice**

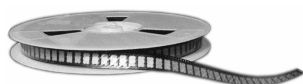
Features:

- 100 Watts
- Lowest Cost
- True Surface Mount
- Alumina Ceramic
- Non-inductive Resistive Element
- Low VSWR
- 100% Tested

Outline Drawing

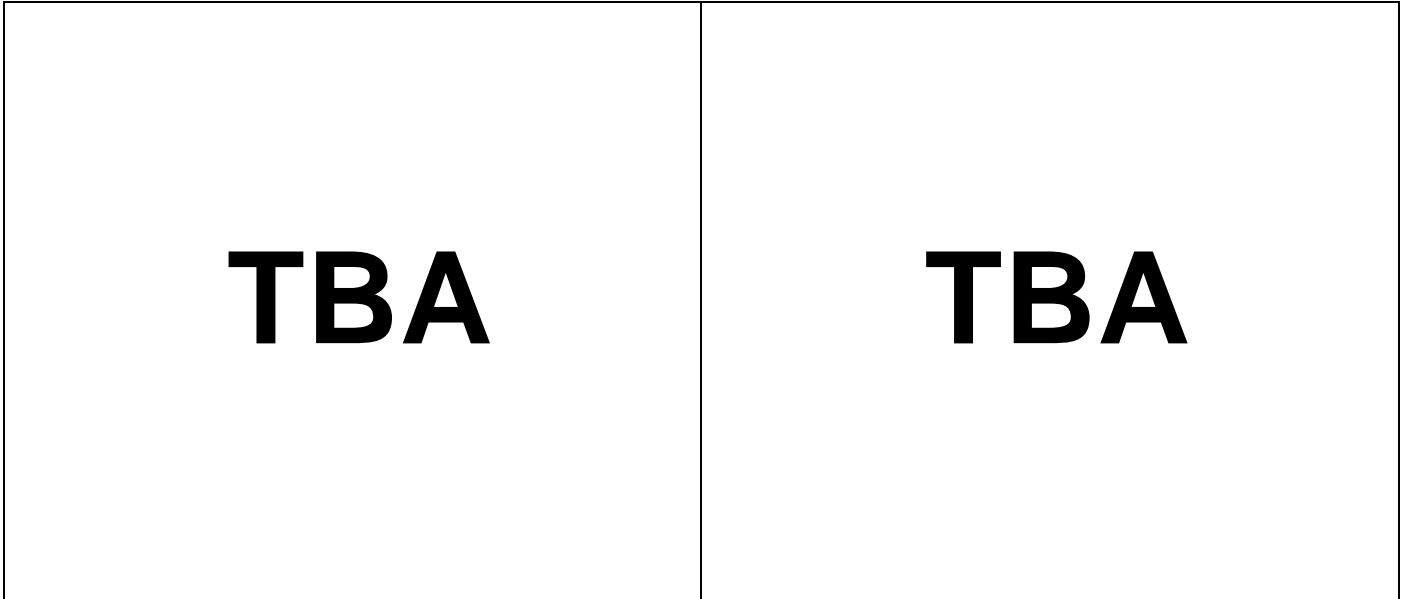


Rev. 9/30/03

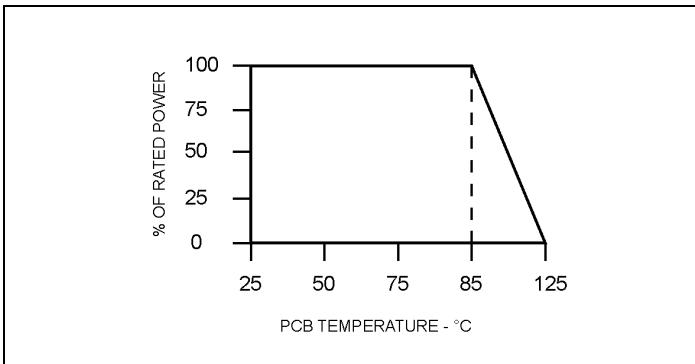




Typical Performance:



Power De-rating:



Tape & Reel:



Mounting Footprint and Procedure:

Dimension given in inches [millimeters]
For best thermal performance the PCB should be soldered to the heat sink.

MOUNTING PROCEDURE

1. Drill thermal vias through PCB and fill with solder, such as SN63 type.
2. Solder part in place using SN63 type solder with controlled temperature iron (700°F).
3. To ensure good thermal connectivity to heat sink, which is critical for proper operation drill and tap heatsink and mount PCB board to heat sink using screws.

